Special Issue

Surface and Bulk Acoustic Wave Devices

Message from the Guest Editors

Surface Acoustic Wave (SAW) and Bulk Acoustic Wave (BAW) devices are pivotal in various applications across telecommunications, consumer electronics, and sensor systems. These devices capitalize on acoustic waves to provide solutions for signal processing, sensing, and actuation at microscale levels. In this Special Issue, we aim to showcase cutting-edge research that highlights the development, optimization, and application of SAW and BAW devices. Contributions may cover a range of topics including, but not limited to, novel fabrication techniques, material innovations, theoretical modeling, and application-driven studies of these devices in new and existing fields. We invite researchers and practitioners to share their insights and findings that contribute to pushing the boundaries of what is possible with acoustic wave technology.

Guest Editors

Dr. Jinkai Chen

Prof. Dr. Shurong Dong

Dr. Hao Jin

Deadline for manuscript submissions

closed (30 June 2025)



Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0 CiteScore 6.0 Indexed in PubMed



mdpi.com/si/203431

Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

mdpi.com/journal/micromachines





an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed



About the Journal

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Editor-in-Chief

Prof. Dr. Ai-Qun Liu

Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China

Author Benefits

High Visibility:

indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

Journal Rank:

JCR - Q2 (Instruments and Instrumentation) / CiteScore - Q1 (Mechanical Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 17.2 days after submission; acceptance to publication is undertaken in 1.9 days (median values for papers published in this journal in the first half of 2025).

